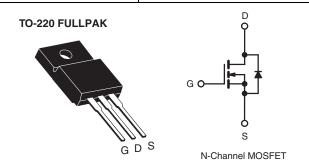


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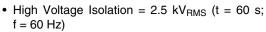
Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	900			
$R_{DS(on)}\left(\Omega\right)$	V _{GS} = 10 V	8.0		
Q _g (Max.) (nC)	38			
Q _{gs} (nC)	4.7			
Q _{gd} (nC)	21			
Configuration	Single			



FEATURES

· Isolated Package





RoHS'

- · Dynamic dV/dt Rating
- Low Thermal Resistance
- Lead (Pb)-free Available

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 FULLPAK eliminates the need for additional insulating hardware in commercial-industrial applications. The molding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The FULLPAK is mounted to a heatsink using a single clip or by a single screw fixing.

ORDERING INFORMATION			
Package	TO-220 FULLPAK		
Lead (Pb)-free	IRFIBF20GPbF		
Lead (FD)-liee	SiHFIBF20G-E3		
SnPb	IRFIBF20G		
JIIF D	SiHFIBF20G		

PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V_{DS}	900	V	
Gate-Source Voltage	V_{GS}	± 20	1 V		
Continuous Drain Current	V_{GS} at 10 V $T_C = 25 ^{\circ}C$	I _D -	1.2	А	
	V_{GS} at 10 V $T_C = 100 ^{\circ}C$		0.79		
Pulsed Drain Current ^a	I _{DM}	4.8			
Linear Derating Factor		0.24	W/°C		
Single Pulse Avalanche Energy ^b	E _{AS}	150	mJ		
Repetitive Avalanche Current ^a	I _{AR}	1.2	Α		
Repetitive Avalanche Energy ^a	E _{AR}	3.0	mJ		
Maximum Power Dissipation	T _C = 25 °C	P_D	30	W	
Peak Diode Recovery dV/dtc	dV/dt	1.5	V/ns		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature)	for 10 s		300 ^d		
Mounting Torque	6-32 or M3 screw		10	lbf ⋅ in	
	6-32 OF IVIS SCIEW		1.1	N · m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 196 mH, R_G = 25 Ω , I_{AS} = 1.2 A (see fig. 12).
- c. $I_{SD} \le 1.7$ A, $dI/dt \le 70$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C.
- d. 1.6 mm from case.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply

IRFIBF20G, SiHFIBF20G

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	65	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	4.1	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static		•					
Drain-Source Breakdown Voltage	V _{DS}	V _{GS}	900	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	1.1	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
		V _{DS} =	V _{DS} = 900 V, V _{GS} = 0 V		-	100	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 720 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	500	μΑ
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 0.72 A ^b	-	-	8.0	Ω
Forward Transconductance	9 _{fs}	V _{DS} =	V _{DS} = 50 V, I _D = 0.72 A ^b		-	-	S
Dynamic		1				•	
Input Capacitance	C _{iss}	$V_{GS} = 0 V$,		-	490	-	_
Output Capacitance	C _{oss}	1	$V_{DS} = 25 \text{ V},$		55	-	
Reverse Transfer Capacitance	C _{rss}	f = 1.0 MHz, see fig. 5		-	18	-	pF
Drain to Sink Capacitance	С		f = 1.0 MHz	-	12	-	
Total Gate Charge	Qg		I _D = 1.7 A, V _{DS} = 360 V, see fig. 6 and 13 ^b	-	-	38	nC
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V		-	-	4.7	
Gate-Drain Charge	Q _{gd}	1		-	-	21	
Turn-On Delay Time	t _{d(on)}				8.0	-	ns
Rise Time	t _r	$V_{DD} = 450 \text{ V}, I_{D} = 1.7 \text{ A},$ $R_{G} = 18 \Omega, R_{D} = 280 \Omega,$ see fig. 10^{b}		-	21	-	
Turn-Off Delay Time	t _{d(off)}			-	56	-	
Fall Time	t _f			-	32	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	
Internal Source Inductance	L _S			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	s	1				•	
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	1.2	- A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	4.8	
Body Diode Voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 1.2 \text{A}, V_{GS} = 0 \text{V}^{\text{b}}$		-	-	1.5	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 1.7 A, dl/dt = 100 A/μs ^b		-	350	530	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	0.85	1.3	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %.





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

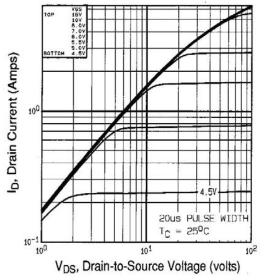


Fig. 1 - Typical Output Characteristics, $T_C = 25~^{\circ}C$

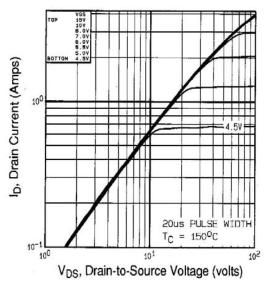


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C

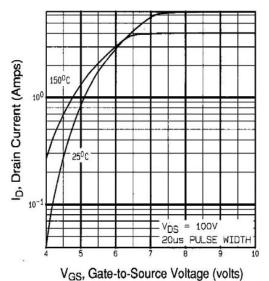


Fig. 3 - Typical Transfer Characteristics

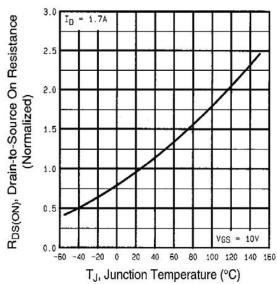


Fig. 4 - Normalized On-Resistance vs. Temperature

IRFIBF20G, SiHFIBF20G

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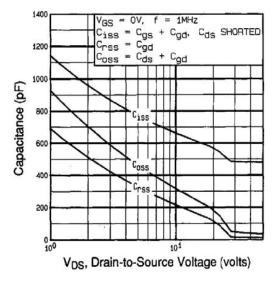


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

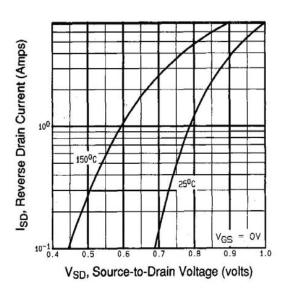


Fig. 7 - Typical Source-Drain Diode Forward Voltage

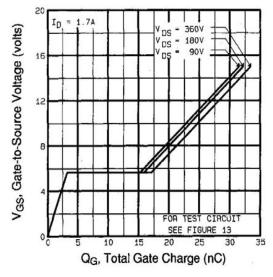


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

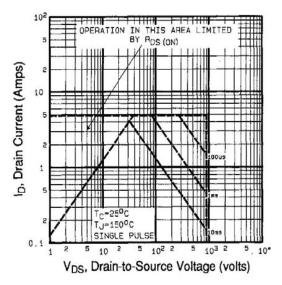


Fig. 8 - Maximum Safe Operating Area



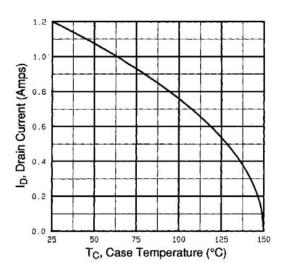


Fig. 9 - Maximum Drain Current vs. Case Temperature

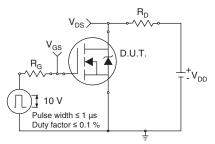


Fig. 10a - Switching Time Test Circuit

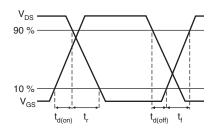


Fig. 10b - Switching Time Waveforms

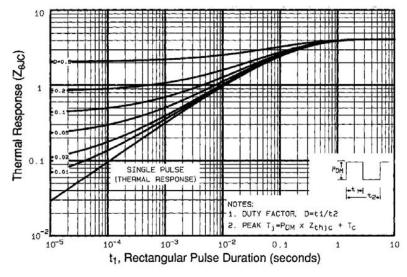


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

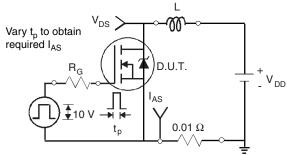


Fig. 12a - Unclamped Inductive Test Circuit

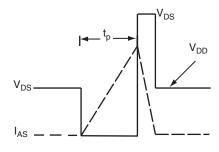


Fig. 12b - Unclamped Inductive Waveforms

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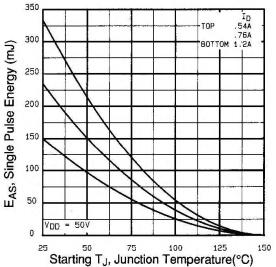


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

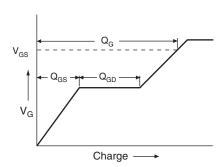


Fig. 13a - Basic Gate Charge Waveform

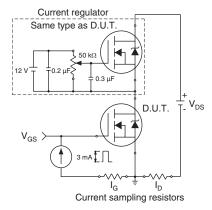
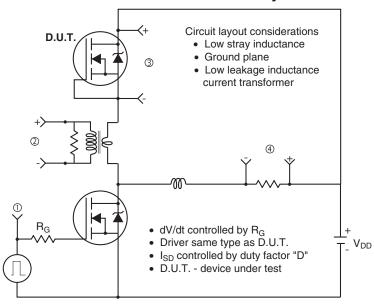


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



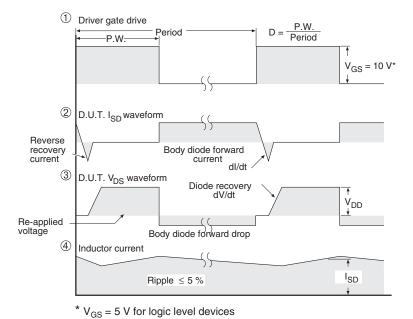


Fig. 14 - For N-Channel

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